

Patent Abstracts of Japan

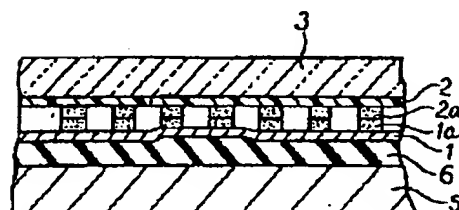
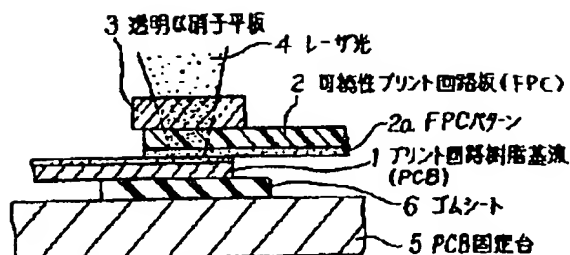
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TITLE : METHOD AND DEVICE FOR LASER
 SOLDERING



ABSTRACT : PURPOSE: To accurately bond a print pattern and improve reliability by placing an elastic flat plate on the back of a printed circuit resin board, aligning by pressing the connecting part using a glass plate from the rear of a flexible printed circuit board and irradiating laser beams along the surface of the bonding part.

CONSTITUTION: A rubber sheet 6 is placed on the surface of a flat fixed table 5, then, a printed circuit resin board (PCB) 1 is mounted on the top of the rubber sheet 6 permitting a print pattern 1a to be the top. Flexible printed circuit board (FPC) 2 is overlapped so as to permit the print pattern 2a of the FPC 2 to be correctly bonded with the PCB1, the FPC2 is pressed on the PCB1 below through a transparent glass flat plate 3 and the both print patterns 1a and 2a are aligned. Then, laser beams 4 are irradiated from the rear of the transparent glass plate 3 by the fixed power, spot radius and scanning speed, which are previously set. Thus, the solder deposited on the connecting edge part of the print pattern 2a forms solder film on the surface and side planes of the print pattern 1a of the PCB1 by the suitable thickness and the connection is completed.

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